PTO/SB/17 (10-04v2)
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FEE	TRANSMITTAL	
]	FOR FY 2005	

Effective 10/01/2004. Patent fees are subject to annual revision. nall entity status. See 37 CFR 1.27.

Applicant Claims small entity status.	Sec 37	CFR 1.27.
TOTAL AMOUNT OF PAYMENT		(\$) 110.00

Signature

	Complete if Known	
Application Number	10/656,239	
Filing Date	September 8, 2003	
First Named Inventor	Hisashi OHTANI et al.	
Examiner Name	D. Le	
Group Art Unit	2818	
Attorney Docket No.	0756-7198	

Date

10-26-04

METHOD OF PAYMENT							FEE CALCULATION (continued)		
1. The Commissioner is hereby authorized to charge indicated			3.	3. ADDITIONAL FEES					
	credit any ove	rpayments to:		Larg	ge	Small	1		
			1_	Enti	•	Entity	y		
Deposit	50 2290		Fee	Fee		Fee	Fee Description	Fee Paid	
Account Number	50-2280		Cod	e (\$)	Code	<b>(\$)</b>	ree Description	reeraid	
Number			1051	130	2051	65	Surcharge late filing fee or oath		
			1052	2 50	2052	25	Surcharge – late provisional filing fee or cover sheet		
Deposit	Robinson	Intellectual Property			1053				
Account Name	Law Offi		1053	130	1053	130	Non-English specification		
Ivanic			1						
E Charge	A A d disiana	I Fac Bassierd	1812	2,520	1812		For filing a request for ex parte reexamination		
	Any Additional 7 CFR 1.16 and		1804	920*	1804	920*	Requesting publication of SIR prior to Examiner action		
	verpayments	4 1.17 and	1805	1,840*	1805	1,840*	Requesting publication of SIR after Examiner action		
l			125	110	2251	55	Extension for reply within first month	-	
	nt claims small	entity status.	1.23						
	CFR 1.27		1252	2 430	2252	215	Extension for reply within second month		
•	nt Enclosed:	<u>_</u>							
∠ Check	☐ Credit	Card Money Other			2253		Extension for reply within third month		
		Order	1254	1,530	2254	765	Extension for reply within fourth month		
	FEE (	CALCULATION	125	2,080	2255	1040	Extension for reply within fifth month		
1. BASIC FIL	ING FEE		140	340	2401	170	Notice of Appeal		
Large Entity	Small Entit	ty	1402	340	2402	170	Filing a brief in support of an appeal		
Fee Fee	Fee Fee		1403	3 300	2403	150	Request for oral hearing		
Code (\$)	Code (\$)	Fee Paid	_						
1001 790	2001 395	Utility filing fee		1,510	1451	•	Petition to institute a public use proceeding		
1002 350	2002 175	Design filing fee	1452	2 110	2452	55	Petition to revive – unavoidable		
1003 550	2003 275	Plant filing fee	1453	3 1,370	2453	685	Petition to revive - unintentional		
1004 790	2004 395	Reissue filing fee	150	1,370	2501	685	Utility issue fee (or reissue)		
1005 160	2005 80	Provisional filing fee	1502	490	2502	245	Design issue fee		
1005 100	2003 80	Provisional limig lee	150	3 660	2503	330	Plant issue fee		
			1460	130	1460	130	Petitions to the Commissioner		
SUBTOTAL (1) (\$)									
2. EXTRA CLAIM FEES			180		1807		Processing fee under 37 CR 1.17(q)		
		Fee from	1800	5 180	1806	180	Submission of Information Disclosure Stmt		
Total Claims Extra Claims below Fee Paid    Total Claims   -20** =   X   \$18   =			802	1 40	8021	40	Recording each patent assignment per property (times		
			J   80%	1 40 60	8021	40	number of properties)		
Independent	-3**=	X \$88 =	1809	790	2809	395	Filing a submission after final rejection (37 CFR		
Claims			, l				§ 1.129(a))		
Multiple Depende	ent	=	1810	790	2810	395	For each additional invention to be examined (37 CFR		
Large Entity	Small Enti	fr.	180	l 790	2801	305	§ 1.29(b)) Request for Continued Examination (RCE)		
Fee Fee	Fee Fee		1 100	,,,,	2001	3,3	Addass to: Commisse Disamission (ACC-)		
Code	(\$) Code	(\$)	1803	900	1802	900	Request for expedited examination of a design		
1002 10	2202 0	CI :					application	6110.00	
1202 18	2202 9		Oth	er fee (sp	ecify) <u>T</u>	erminal	<u>Disclaimer</u>	\$110.00	
1201 88	2201 44	Independent claims in excess of 3						<del></del>	
1203 300	2203 150	Multiple dependent claim, if not pa	d Re	duced by	Basic I	Filing Fe	ee Paid SUBTOTAL (3) (\$) 110.00		
1204 88	2204 44	** Reissue independent claims over	1				<u></u>		
	****	original patent					CERTIFICATE OF MAILING		
1205 18 2205 9 ** Reissue claims in excess of 20 and over original patent			I	hereby o	ertify that	CERTIFICATE OF MAILING t this correspondence is being deposited with the United States Postal S	ervice with		
			suffi	cient posta	ge as first	t class ma	ail in an envelope addressed to Commissioner for Patents, P.O. Box 14	50, Alexandria,	
SUBTOTAL (2) (\$)			_   _ <b>V</b> A :	22313-1450	on I	<i>∂</i> √ <i>6</i>	104 (Kell Julan)		
••or number previously paid, if greater; For Reissues, see above									
SUBMITTED BY							Complete (if applicable)		
SOBMITTED		Eric I Pohinson	Res	gistratio	n No	20	285 (571) 434-6780		
Name (Print/T)	ipe)	Eric J. Robinson		jisu auo Iornev/A		30	7283 Telephone (371) 434-0789	,	



Docket No. 0756-7198

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

	In re PATENT application of			)			
	Hisashi Ol	HTANI et al.	)				
	Serial No. 10/656,239			) Art Unit: 2818			
	Filed: September 8, 2003		) Examiner: D. Le				
	For:	SEMICONDUCTOR	DEVICE	AND	FABRICATING	METHOD	
THEREOF)							
11/30/2004 SMINA	1551 00000003	10656239					

## **TERMINAL DISCLAIMER**

Honorable Assistant Commissioner for Patents

110.00 DP

Washington, D. C. 20231

Sir:

01 FC:1814

I, Dr. Shunpei Yamazaki, having a place of business at Semiconductor Energy Laboratory Co., Ltd., 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan, state that I am authorized to sign on behalf of the assignee of this invention and that the

Assignment referred to below has been reviewed and certify that, to the best of my knowledge and belief, the entire right, title and interest in the above-identified application is in the name of Semiconductor Energy Laboratory Co., Ltd. by virtue of an Assignment recorded in the U.S. Patent and Trademark Office at Reel 9502, Frame 0416-0418.

Semiconductor Energy Laboratory Co., Ltd. hereby disclaims, except as provided below, the terminal part of the statutory term of any patent granted on the instant application, which would extend beyond the expiration date of the full statutory term defined in 35 U.S.C. 154 to 156 and 173, as presently shortened by any terminal disclaimer, of prior Patent No. 6,465,288.

Docket No. 0756-7198

Semiconductor Energy Laboratory Co., Ltd. hereby agrees that any patent so granted on the instant application shall be enforceable only for and during such period that it and prior Patent No. 6,465,288 are commonly owned. This agreement runs with any patent granted on the instant application and is binding upon the grantee, its successors or assigns.

In making the above disclaimer, Semiconductor Energy Laboratory Co., Ltd. does not disclaim the terminal part of any patent granted on the instant application that would extend to the expiration date of the full statutory term as defined in 35 U.S.C. 154 to 156 and 173 of the prior patent, as presently shortened by any terminal disclaimer, in the event that it later expires for failure to pay a maintenance fee, is held unenforceable, is

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found invalid by a court of competent jurisdiction, is statutorily disclaimed in whole or

terminally disclaimed under 35 CFR 1.321, has all claims cancelled by a reexamination

certificate, is reissued, or is in any manner terminated prior to the expiration of its full

statutory term as presently shortened by any terminal disclaimer.

I hereby declare that all statements made herein of my own knowledge are true

and that all statements made on information and belief are believed to be true; and

further that these statements were made with the knowledge that willful false statements

and the like so made are punishable by fine or imprisonment, or both, under Section

1001 of Title 18 of the United States Code and that such willful false statements may.

jeopardize the validity of the application or any patent issuing thereon.

11/12/2004

Date

Name: Shunpei Yamazaki

Title: President

Company Name: Semiconductor

Energy

Laboratory Co., Ltd.